

Title (en)

PROCESS FOR ACTIVATING A SUBSTRATE FOR ELECTROLESS DEPOSITION OF A CONDUCTIVE METAL

Publication

EP 0163089 B1 19880810 (EN)

Application

EP 85104589 A 19850417

Priority

US 60379184 A 19840425

Abstract (en)

[origin: EP0163089A2] A substrate is activated by providing a first resist thereon; followed by a second resist on the first resist. The first and second resists differ in their solubility characteristics. The resists are exposed to imaging radiation and developed. The substrate is seeded and the second resist layer is removed, thereby removing seeder, except from exposed areas of the substrate.

IPC 1-7

H05K 3/18; G03F 7/02; C23C 18/16

IPC 8 full level

G03F 7/095 (2006.01); **H05K 1/03** (2006.01); **H05K 3/04** (2006.01); **H05K 3/18** (2006.01)

CPC (source: EP)

G03F 7/095 (2013.01); **H05K 3/048** (2013.01); **H05K 3/184** (2013.01); **H05K 2203/0577** (2013.01)

Cited by

DE4339019A1; EP1431018A4; EP0542149A3; EP1462859A3; EP0483484A3; EP0817549A3

Designated contracting state (EPC)

DE FR GB

DOCDB simple family (publication)

EP 0163089 A2 19851204; **EP 0163089 A3 19870729**; **EP 0163089 B1 19880810**; DE 3564363 D1 19880915; JP H048958 B2 19920218; JP S60231388 A 19851116

DOCDB simple family (application)

EP 85104589 A 19850417; DE 3564363 T 19850417; JP 1563285 A 19850131